Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

If Sil-Pad part number SP1500-0.020-00-0404 is used, the pads need to be cut into 2 inch squares.

Apply thin layer of SA-1000 between Aluminum Plate MCH003 and PCB during installation.

See P1RO15 Assembly Guide for build up on L1 and associated hardware.

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>bq50002 + bq500311</td>
</tr>
</tbody>
</table>

**COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.**

ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-00623</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>IGNORE</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 10/15/2015 8:47:10 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
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